

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5780153

|   |                                    |                       |
|---|------------------------------------|-----------------------|
| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                     |                       |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                         |                       |
| <b>CONVEYING PARTY DATA</b>   |                                    |                       |
|   | <b>Name</b>                        | <b>Execution Date</b> |
|   | ULRICH DUEMLER                     | 10/19/2019            |
|   | BORTECENE TERLEMEZ                 | 10/18/2019            |
| <b>RECEIVING PARTY DATA</b>   |                                    |                       |
| <b>Name:</b>  | INTEGRATED DEVICE TECHNOLOGY, INC. |                       |
| <b>Street Address:</b>  | 6024 SILVER CREEK VALLEY ROAD      |                       |
| <b>City:</b>  | SAN JOSE                           |                       |
| <b>State/Country:</b>   | CALIFORNIA                         |                       |
| <b>Postal Code:</b>   | 95138                              |                       |
| <b>PROPERTY NUMBERS Total: 1</b>  |                                    |                       |
|   | <b>Property Type</b>               | <b>Number</b>         |
|   | Application Number:                | 16395781              |
| <b>CORRESPONDENCE DATA</b>  |                                    |                       |
| <b>Fax Number:</b>  |                                    |                       |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |                                    |                       |
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| <b>Correspondent Name:</b>  | GARY J. EDWARDS                    |                       |
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| <b>ATTORNEY DOCKET NUMBER:</b>  | 70107.593US01 D5283-US             |                       |
| <b>NAME OF SUBMITTER:</b>   | RYAN BORDON                        |                       |
| <b>SIGNATURE:</b>   | /Ryan Bordon/                      |                       |
| <b>DATE SIGNED:</b>   | 10/21/2019                         |                       |
| <b>Total Attachments: 2</b>   |                                    |                       |
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| source=70107_593US01_D5283_US_Assignment#page2.tif  |                                    |                       |

## ASSIGNMENT

WHEREAS, WE,

- (1) Ulrich DUEMLER of Zurich, SWITZERLAND  
(2) Bortecene TERLEMEZ of Zurich, SWITZERLAND

have invented certain improvements in

## PHOTODETECTOR CIRCUIT

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_ of even date filed herewith; and  
X filed on April 26, 2019 and assigned application serial number 16/395,781; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Integrated Device Technology, Inc., a Delaware corporation, located at 6024 Silver Creek Valley Road in San Jose, California 95138, U.S.A., (hereinafter known as "Assignee") is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said Assignee, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.


AND WE HEREBY further covenant and agree that we will communicate to said Assignee, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS THEREOF, each inventor has affixed his signature.

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First Inventor Name: Ulrich DUEMLER  
Residence Address: Gigoptix-Helix AG, Seefeldstrasse 45, CH-8008, Zurich, Switzerland

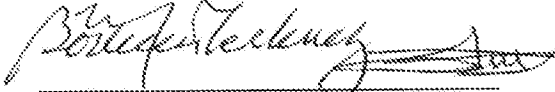
Dated: 10/21/2019

  
Inventor Signature

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Second Inventor Name: Bortecene TERLEMEZ  
Residence Address: Gigoptix-Helix AG, Seefeldstrasse 45, CH-8008, Zurich, Switzerland

Dated: 10/18/2019

  
Inventor Signature